

ABSTRACT

RESIN COMPOSITION, LAYERED PRODUCT, MULTILAYER PRINTED WIRING BOARD, MULTILAYER FLEXIBLE WIRING BOARD AND MANUFACTURING METHOD OF THE SAME

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A resin composition containing (A) a polyimide having acidic functional groups and (B) a compound having functional groups that react with the acidic functional groups, where (a) a solution rate in 3 mass% aqueous sodium hydroxide at 45°C is 10 0.95 or more after a heat history of 90°C for 10 minutes with the solution rate before the heat history assumed to be 1, (b) the solution rate in 3 mass% aqueous sodium hydroxide at 45°C ranges from 0.001 $\mu\text{m}/\text{sec}$ to 0.02 $\mu\text{m}/\text{sec}$ after the heat history of 180°C for 60 minutes, (c) a bleed-out amount is 50 mg/m^2 or 15 less in storing at 40°C for 2 weeks after the heat history of 180°C for 60 minutes, and (d) a thermogravimetric decrease at 260°C is 2.0% or less in measuring on a temperature rising condition of 10°C/min from 40°C by thermogravimetric analysis (TG). When a multilayer flexible wiring board is manufactured 20 using the resin composition, it is possible to obtain the resin layer excellent in alkali processability, embeddability in press, heat resistance, bendability, insulation reliability, and adhesion to the conductive layer.

25 No figure to accompany abstract